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December 2008

FDS8882

N-Channel PowerTrench[®] MOSFET 30 V, 9 A, 20.0 m Ω

Features

- Max $r_{DS(on)} = 20.0 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 9 \text{ A}$
- Max $r_{DS(on)}$ = 22.5 m Ω at V_{GS} = 4.5 V, I_D = 8 A
- \blacksquare High performance trench technology for extremely low $r_{\mbox{DS}(\mbox{on})}$ and fast switching
- High power and current handling capability
- Termination is Lead-free and RoHS Compliant

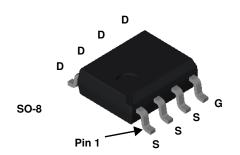
General Description

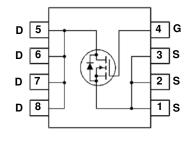
The FDS8882 has been designed to minimize losses in power conversion application. Advancements in both silicon and package technologies have been combined to offer the lowest $r_{\text{DS}(on)}$ while maintaining excellent switching performance.

Applications

- Notebook System Regulators
- DC/DC Converters







MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V _{DS}	Drain to Source Voltage			30	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous -Pulsed			9	Δ.
ID				21	A
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	32	mJ
D	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1b)	1.0	VV
T _J , T _{STG}	Operating and Storage Junction Temper	erature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	-C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS8882	FDS8882	SO8	13 "	12 mm	2500 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25 °C		4		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.7	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-6		mV/°C
		V _{GS} = 10 V, I _D = 9 A		13.2	20.0	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 8 \text{ A}$		16.6	22.5	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}, T_J = 125 \text{ °C}$		18.5	28.0	
9FS	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 9 \text{ A}$		36		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 45 V V 0 V	707	940	рF
C _{oss}	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	138	185	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11/12	88	135	pF
R_g	Gate Resistance		1.8		Ω

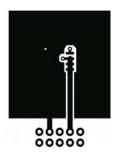
Switching Characteristics

t _{d(on)}	Turn-On Delay Time		7	14	ns
t _r	Rise Time	$V_{DD} = 15 \text{ V}, I_{D} = 9 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	3	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, H _{GEN} = 6 12	19	35	ns
t _f	Fall Time		4	10	ns
Q_g	Total Gate Charge	V _{GS} = 0 V to 10 V	14	20	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$ $V_{DD} = 15 \text{ V},$ $I_{D} = 9 \text{ A}$	8	11	nC
Q _{gs}	Gate to Source Charge	ID = 9 A	2.2		nC
Q _{gd}	Gate to Drain "Miller" Charge		2.8		nC

Drain-Source Diode Characteristics

V _{SD} Source to Drain Diode Forward Voltage	Source to Drain Diode, Forward Voltage	V _{GS} = 0 V, I _S = 9 A	0.8	1.2	V
	V _{GS} = 0 V, I _S = 2.1 A	0.7	1.2	V	
t _{rr}	Reverse Recovery Time	-I _E = 9 A, di/dt = 100 A/μs	17	31	ns
Q _{rr}	Reverse Recovery Charge	- I _F = 9 A, αl/αι = 100 A/μS	6	12	nC

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width < 300 $~\mu s,$ Duty cycle < 2.0%. 3. Starting T $_J$ = 25 °C, ~L = 1 mH, I_{AS} = 8 Å, V_{DD} = 27 V, V_{GS} = 10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

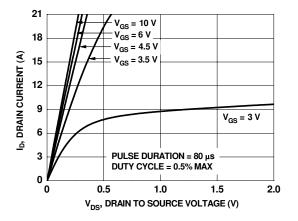


Figure 1. On Region Characteristics

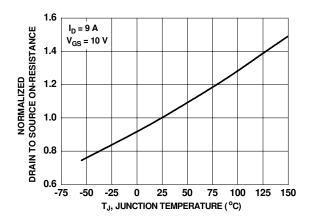


Figure 3. Normalized On Resistance vs Junction Temperature

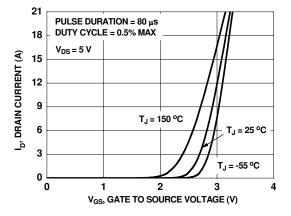


Figure 5. Transfer Characteristics

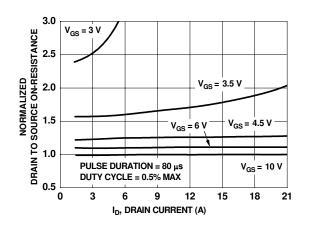


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

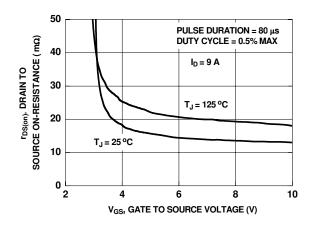


Figure 4. On-Resistance vs Gate to Source Voltage

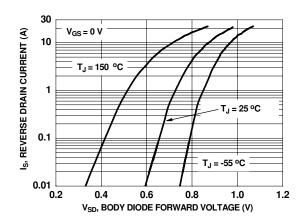


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

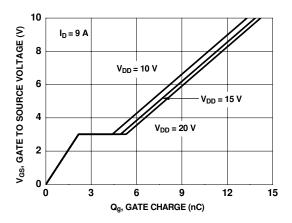


Figure 7. Gate Charge Characteristics

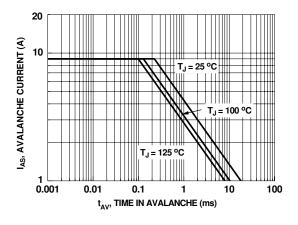


Figure 9. Unclamped Inductive Switching Capability

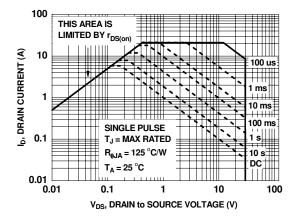


Figure 11. Forward Bias Safe Operating Area

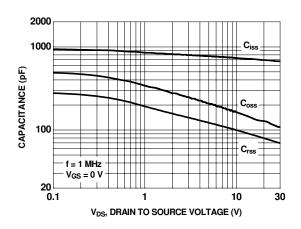


Figure 8. Capacitance vs Drain to Source Voltage

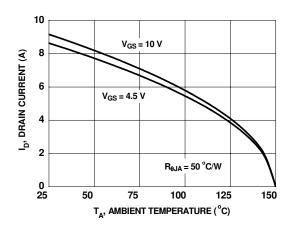


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

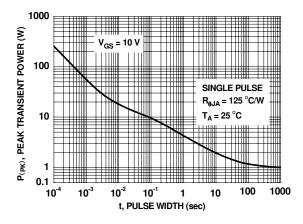


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

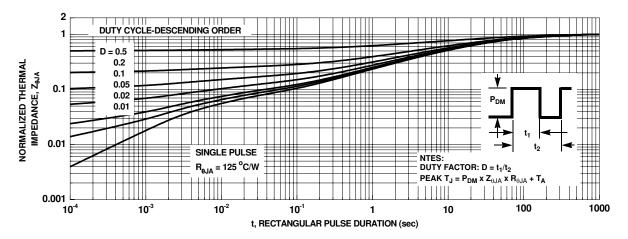


Figure 13. Junction-to-Ambient Transient Thermal Response Curve





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